OIF's CEI 56G Interfaces – Key Building Blocks for Optics in the 400G Data Center

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Agenda

- Interconnect challenges facing next-generation 200G/400G data centers
 - **Overview of OIF's CEI-56G projects**
- **56G VSR chip-to-module example**
- Other OIF projects addressing the Data Center
- Summary

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Data Center (DC) Trends

- 2015 Data Center facts
 - DC traffic > 5 ZB in 2015, much of that being intra-DC
 - Inter-DC traffic growth to increase at a higher rate than intra-DC
 - DC SDN based networks
- Data center interconnect (DCI) becoming a significant portion of DC overall cost and power consumption
- Expect significant growth of DCI market addressing geographically dispersed sites
- 10G/40G/100G in deployment now, 25G/50G/200G/400G on the horizon



Data Center Interconnect Challenges

Power efficiency (pJ/bit or mW/Gb/s)

Port density (Gb/s/mm²)

Reach (km)

Cost efficiency (\$/Gb/s)



Technologies Enabling Future DC Client Interconnects

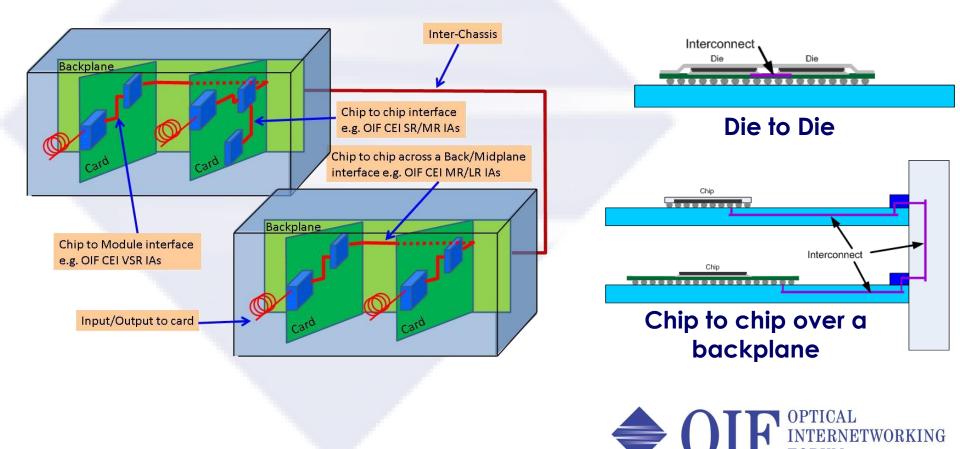
- Electrical passive/active cabled interconnect (e.g. twin-ax)
- Multi-mode/single-mode VCSELs
- Single-mode Si Photonics
- Single-mode Coarse Wavelength Division Multiplexing (CWDM)
- PAM-4 modulation
- System Forward Error Correction (e.g. RS(528,514) FEC)



Next Generation Interconnect Framework

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 Identify the application spaces that might benefit from Implementation Agreements



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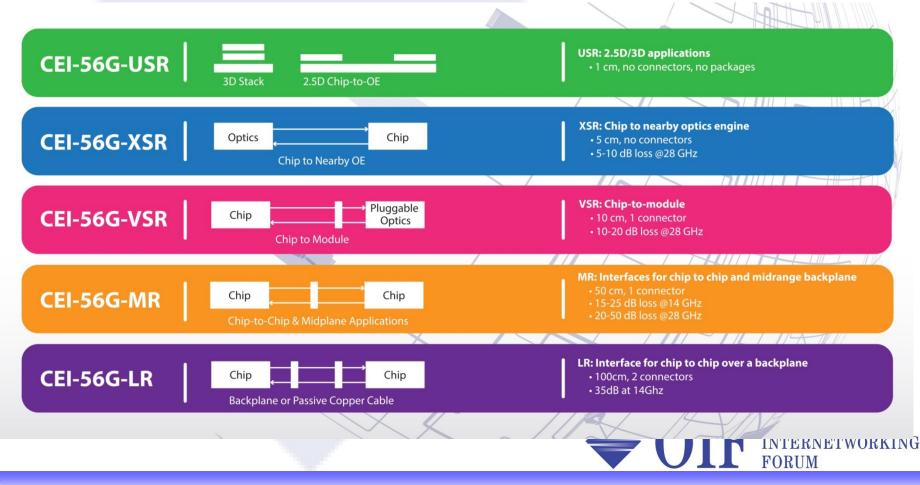
OIF Physical and Link Layer Projects

- CEI 56G Ultra Short Reach (CEI-56G-USR)
- CEI 56G Extra Short Reach (CEI-56G-XSR)
- CEI 56G Very Short Reach (CEI-56G-VSR)
- CEI 56G Medium Reach (CEI-56G-MR)
 - CEI 56G Long Reach (CEI-56G-LR)
- Flex Ethernet Project
- MLG (Multi-Link Gearbox) 3.0
- Intermediate Reach DWDM Framework
- Electro-Mechanical Footprint for Optical Engines in a Chip Scale Package
- CFP2 Analog Coherent Optics Module (CFP2-ACO)
- Integrated Polarization Multiplexed Quadrature Modulated Transmitters for Metro Applications
- High Bandwidth Polarization Multiplexed Quadrature Transmitter
- High Bandwidth Integrated Coherent Receiver



OIF CEI-56G Projects

- **CEI-56G is leading the drive to higher bandwidths**
- Projects underway in five link reaches with multiple modulations



CEI-56G Electrical Modulation Variants

 OIF is pursuing multiple modulation variants for several reaches including NRZ, PAM-4 and ENRZ

Interface	NRZ	PAM-4	ENRZ
CEI-56G-USR	•		
CEI-56G-XSR	•	•	
CEI-56G-VSR	•	•	
CEI-56G-MR	•	•	
CEI-56G-LR		•	•

What about CEI-112G? When will it come and what will enable it?

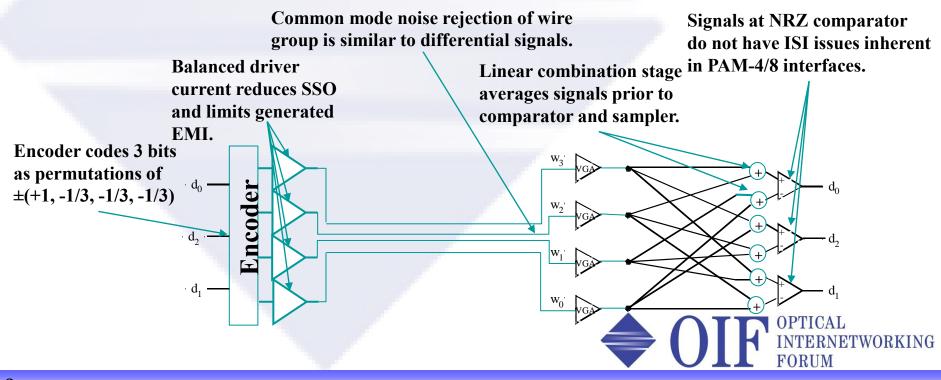


ENRZ Multiwire Code

ENRZ is a 3-bit over wire code that uses a channel composed of 4 correlated wires

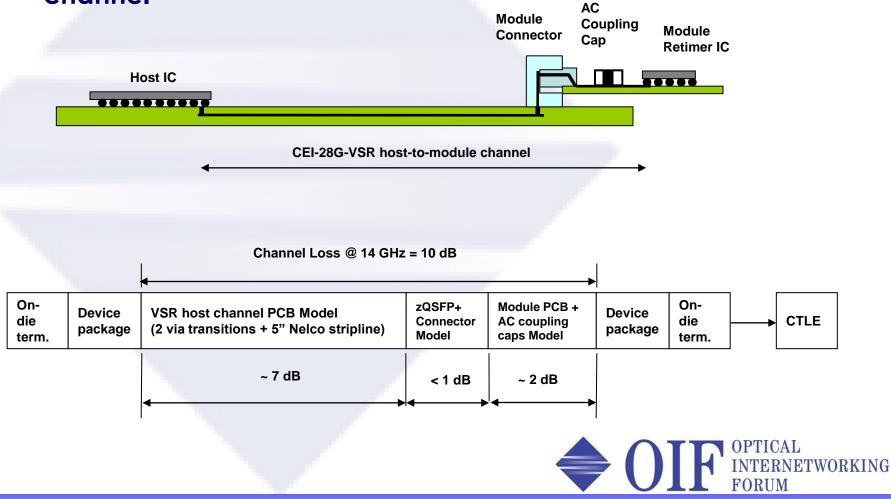
- Bandwidth per wire is higher than differential NRZ at similar baud rate
- Inter-symbol Interference (ISI) is lower than PAM-4/8 interfaces
- Noise rejection characteristics are similar to differential signals

Because of signal integrity advantages, CEI-56G-LR-ENRZ does not require a FEC as is required for other LR variants

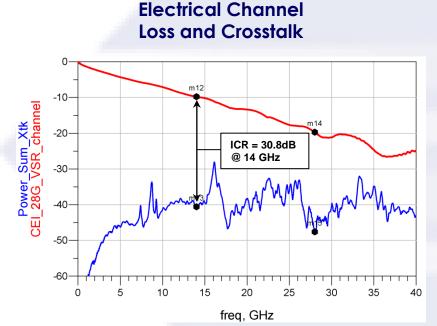


56G VSR/Chip-to-Module Channel

Potential 56G channel based upon present CEI-28G-VSR channel



Challenges of serial 56 Gb/s electrical interconnects



Typical QSFP28 VSR

Interconnect challenges:

- Even premium PCB materials show significant losses for 56 Gb/s NRZ signals
- Package and connector performance/crosstalk will also be an issue
- Cost effective electronics with necessary performance can be an issue at 56 Gb/s

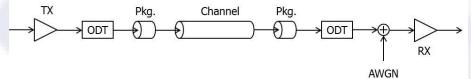
More complex electrical modulation schemes should be considered



56G PAM-4 VSR Channel Simulation Parameters



Serial Link System:



CDR Input Block Diagram:



Simulation setup

- Data pattern: PRBS23
- Signaling format: PAM-4

Jitter

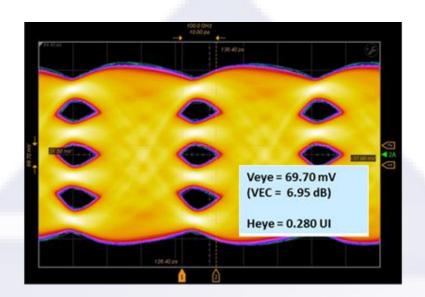
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- TX RJ: 0.18ps RMS
- RX RJ: 0.22ps RMS
- TX DJ: 1.5ps peak-to-peak

Rx Noise

- 3.7e-8 V²/GHz
- Baud rate: 28.0 Gbaud
 - Target BER: 1e-6, 1e-15
 - **Equalization schemes**
 - One-zero and two-pole CTLE with variable DC gain and up to 10dB AC gain at 14GHz





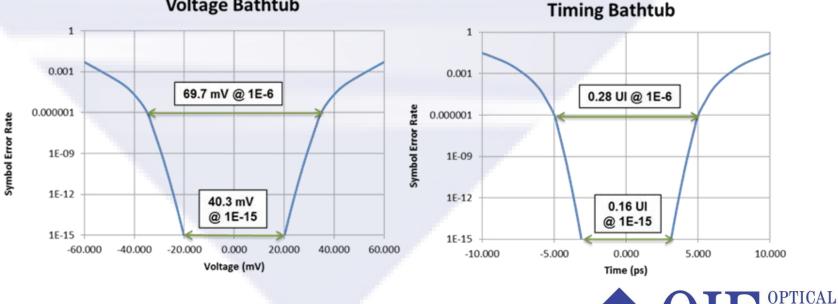
PAM4 VSR Analysis

1E-6 eye diagram at **CDR** slicer input

INTERNETWORKING

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Voltage Bathtub



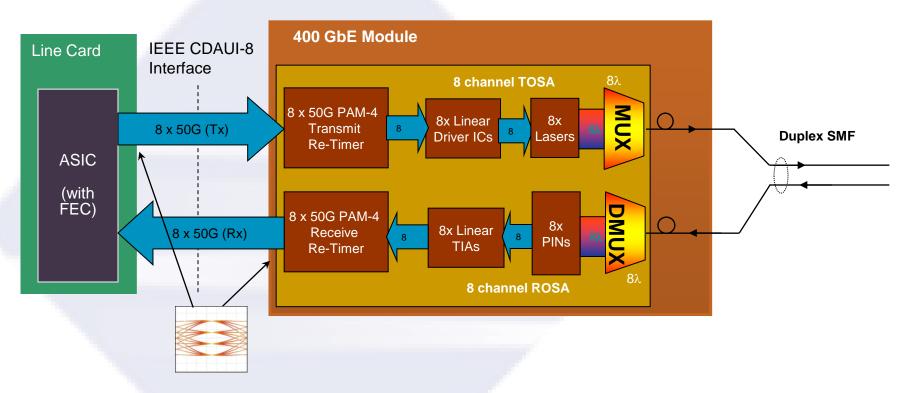
Voltage, Timing Bathtub Curves

IEEE 400G 802.3bs electrical interfaces and optical PMD's

- CDAUI-8 chip-to-module and chip-to-chip electrical interconnects selected as PAM-4 based upon OIF's CEI-56G-VSR-PAM4 and CEI-56G-MR-PAM4, respectively
- 400G FR8/LR8 2km/10km SM PMD's based on 8x 50G PAM-4 modulation with host based FEC
 - 400G PSM4 or DR4 based on 4x 100G PAM-4



IEEE 802.3bs 400G FR8/LR8 Module (1/2)



 CDAUI-8 c2m electrical interface based on CEI-56G-VSR-PAM4 interface

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INTERNETWORKING

- c2c interface based on CEI-56G-MR-PAM4
- FR8/LR8 optical PMD also selected as PAM4

IEEE 802.3bs 400G FR8/LR8 Module (2/2)

400G FR8/LR8 module:

- Initial 400G CDAUI-8 module could be based on a CFP2
 form factor with other options to follow
- This architecture can be largely implemented with present 25 Gb/s optics thus leveraging components developed for the high volume 100 GbE market
- Having both PMA and PMD blocks based on PAM-4 is beneficial from several aspects
- Required FEC in the host IC manages both the optical and electrical links



Possible future client pluggable modules based on 56G VSR host interfaces

50G SFP56

- 1x 56G client interface
- 100G QSFP56, μQSFP
 - 2x 56G client interface
 - 200G QSFP56, µQSFP
 - 4x 56G client interface
- 400G "double" QSFP28 module
 - 8x 56G client interface



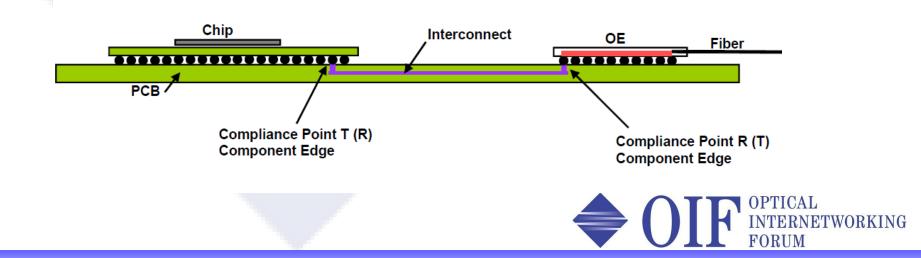
At present QSFP28 is most desirable data center 100G client pluggable

 μQSFP targeting next generation 100G/200G data center client interconnects



CEI-56G-XSR "Chip-to-OE" Introduction

- 56G-XSR goals:
 - Data rate of 39 56 Gb/s
 - BER < 1E-15
 - Short interconnect < 50 mm
 - Interface needs to be optimized for low power
- Related to OIF's "Electro-Mechanical Footprint for Optical Engines in a Chip Scale Package" project



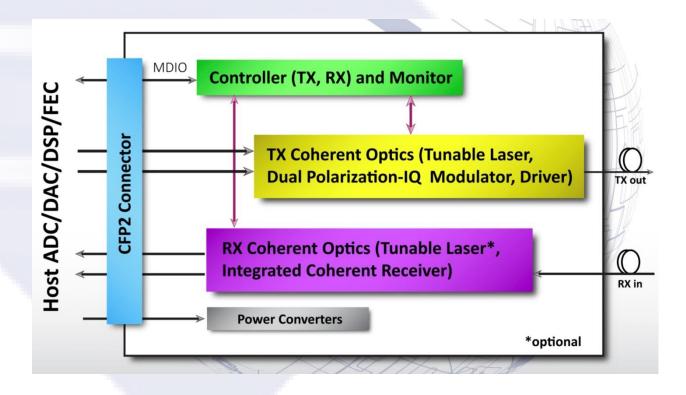
Status of CEI-56G-XSR Specifications

- XSR interface target BER < 1E-15 with no external FEC</p>
- Interconnect is DC-coupled with 92.5 Ω diff impedance
- Interface timing based on a low-speed fbaud/64 common clock, traditional per lane CDR approach not explicitly mandated
- NRZ variant has Tx Vamp 250-400 mVpp, possibly with some Rx equalization
- PAM4 variant has Tx Vamp = 400-600mVpp, with Rx equalization being required



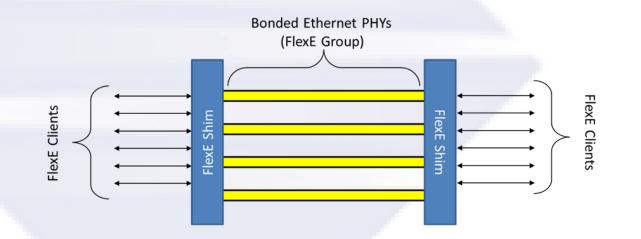
OIF 100G/200G CFP2-ACO Module Form Factor

CFP2-ACO pluggable modules are presently one option addressing the DCI Metro/Regional DWDM market



OIF Flex Ethernet Project

- A mechanism to support a variety of Ethernet MAC rates not corresponding to an existing Ethernet PHY rate
- Can enable bonding of PHYs, sub-rate operation of PHY or channelization within a group of PHYs



Enables applications such as "router-to-transport" connection and intra-DC "fat-pipe"



Summary

- CEI-56G interface specification work is well under way
- Several standards bodies are planning to leverage OIF's work on CEI-56G
- CEI PAM4 interfaces will be key in enabling a solid foundation for next generation 200G/400G client optics
- OIF has several projects under way addressing the future needs of the data center (CFP2-ACO, Flex Ethernet, etc)

